

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Mei-Hsuan LIN</td> <td>02/03/2012</td> </tr> <tr> <td>Chih-Hsun LIN</td> <td>02/03/2012</td> </tr> <tr> <td>Ching-Hua CHU</td> <td>02/03/2012</td> </tr> <tr> <td>Ling-Sung WANG</td> <td>02/03/2012</td> </tr> </tbody> </table>		Name	Execution Date	Mei-Hsuan LIN	02/03/2012	Chih-Hsun LIN	02/03/2012	Ching-Hua CHU	02/03/2012	Ling-Sung WANG	02/03/2012
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI, Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: (703)518-5499          Phone: 7036841111          Email: tsmc@ipfirm.com  <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Lowe Hauptman Ham &amp; Berner, LLP (TSMC)          Address Line 1: 1700 Diagonal Road, Suite 300          Address Line 4: Alexandria, VIRGINIA 22314</p>											
ATTORNEY DOCKET NUMBER:	T5057-606										
NAME OF SUBMITTER:	Randy A. Noranbrock										
Total Attachments: 1 source=efiledassgn2012-04-23#page1.tif											

OP \$40.00 13367989

2011-1175  
Docket No. T5057-606

## ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- |                  |                   |
|------------------|-------------------|
| 1) Mei-Hsuan LIN | 4) Ling-Sung WANG |
| 2) Chih-Hsun LIN |                   |
| 3) Ching-Hua CHU |                   |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

**TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.** having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

### **SALICIDE FORMATION USING A CAP LAYER**

(a) for which an application for United States Letters Patent was filed on 2012-02-07, and identified by United States Patent Application No. 13/367,989; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Mei-Hsuan Lin  
Name: Mei-Hsuan LIN

2012.2.3  
Date:

2) Chih-Hsun Lin  
Name: Chih-Hsun LIN

2012.2.3  
Date:

3) Ching-Hua Chu  
Name: Ching-Hua CHU

2012.2.3  
Date:

4) Ling-Sung Wang  
Name: Ling-Sung WANG

2012.2.3  
Date: